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LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	8	0.20	260	YES
×	2	40	1.02	50	YES
□	3	126	3.20	2	NOT

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	8	0.20	260	YES
×	2	40	1.02	50	YES
□	3	126	3.20	2	NOT

STACK-UP FOR REFERENCE

Layer	Material	Thickness
LAYER 1 L1 TOP	18 UM CU + 18 UM PLATING (35 UM)	1.072 MM ± 10%
CORE	1.0 MM CORE FR-4 LG 135 INC. COP.	
LAYER 4 L16 BOTTOM	18 UM CU + 18 UM PLATING (35 UM)	

NOTES:

1. PRINTED CIRCUIT BOARD MADE FROM NEMA GRADE FR-4 TG 135 EPOXY LAMINATE WITH 35 UM COPPER PLATING AND 1 MM THICKNESS.
2. ALL DIMENSIONS ARE GIVEN IN MILLIMETERS EXCEPT TRACE WIDTH/SPACE
3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE GREEN SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY. EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING WHITE INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
  - \* 2 COPPER LAYERS
  - \* 1 MM BOARD THICKNESS
  - \* REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

Domino Core

Domino Pi

Domino Qi

CC

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Domino Pi

17/06/14 23:22

Gold plated Glass (GMP) / MT (CASC)

Rev. A